



**The 56th Electronic Components  
and Technology Conference**

**May 30 – June 2, 2006  
San Diego, CA USA**

The **56th Electronic Components & Technology Conference** will be held at Sheraton San Diego Hotel & Marina, San Diego, California, USA on May 30 – June 2, 2006. This premier international conference is sponsored jointly by the IEEE Components, Packaging and Manufacturing Technology Society (CPMT) and the Electronic Components, Assemblies, and Materials Association (ECA), the electronic components sector of the Electronic Industries Alliance (EIA).

The audience includes representatives from leading universities and companies eager to stay abreast of rapidly changing and emerging technologies in the electronics field. This is the big annual CPMT Society all-technology meeting. The primary goal of the conference is to offer quality coverage of technological innovations in the areas of packaging design, materials, processes, quality and manufacturing of devices, components and systems. The Program Committee represents a wide variety of disciplines and expertise from the electronics industry. We are committed to assembling the highest quality program for the 56th ECTC, and we have many excellent papers to meet this commitment.

The ECTC Program Committee met on November 3-4, 2005 in Dallas, Texas, USA and reviewed about 550 abstracts submitted for the conference from 21 countries. At the 56th ECTC, over 300 papers will be presented by companies, universities and research institutions from around the world in 36 oral sessions and two poster sessions. These papers will cover a wide spectrum of topics, including electronic components, materials, assembly, packaging, system packaging, optoelectronics, quality & reliability, modeling & simulation, and emerging topics such as nanotechnology and biotechnology.

The ECTC also comprises of professional development courses covering 16 different topics offered by world-class experts in their fields. Participants can catch up with new technology developments and broaden their technical knowledge base. In addition, workshops on Tin-Whiskers and Education, a panel discussion on “3D Packaging and Novel Interconnects”, a plenary session entitled, “Look into the Crystal Ball: Arising New Applications, Technologies and Challenges”, and a seminar on “Advanced Substrate Technologies for SiP/SoP” will be held at the ECTC.

The technical program and professional development courses are supplemented by the technical exhibition corner. Leading companies in the electronic components, materials, and packaging field exhibit their latest technologies and products.

The day before the ECTC sessions begin, the CPMT Society is holding its 9<sup>th</sup> annual International Workshop on Microsystems Packaging Education, better known as the **Academic Conference**. Organized this year by Paul Wesling and Rao Tummala, it provides a venue for professors and instructors from around the world to gather a day early to review new initiatives in teaching undergraduate and grad courses in electronics packaging and manufacturing sciences. Also covered are innovative ways to bring technology to industry practitioners. We invite all university people to arrive “a day early” at ECTC to participate in this no-cost event.

*Please visit [www.ectc.net](http://www.ectc.net) for additional conference information. Registration for the conference starts in January 2006. Early registration discount applies until May 12, 2006.*